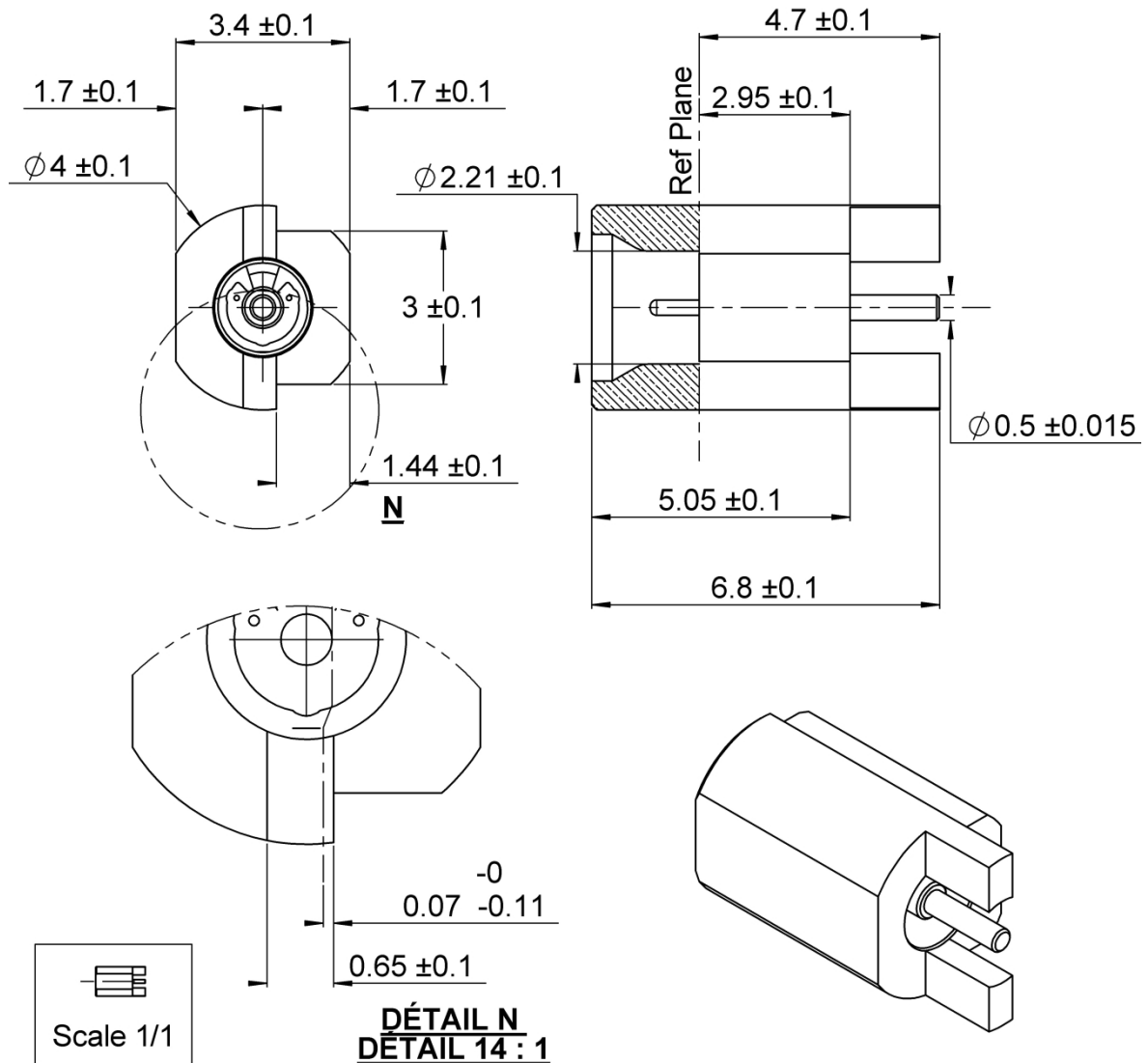


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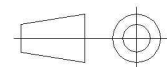
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All dimensions are in mm.



| COMPONENTS     | MATERIALS               | PLATING (μm) |
|----------------|-------------------------|--------------|
| Body           | <b>BERYLLIUM COPPER</b> | <b>N2PGR</b> |
| Center contact | <b>BERYLLIUM COPPER</b> | <b>N2PGR</b> |
| Outer contact  |                         |              |
| Insulator      | <b>PEEK</b>             |              |
| Gasket         |                         |              |
| Others parts   |                         |              |
| -              | -                       | -            |
| -              | -                       | -            |

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### PACKAGING

| Standard   | Unit | Other             |
|------------|------|-------------------|
| <b>500</b> | -    | <b>Contact us</b> |

### ELECTRICAL CHARACTERISTICS

|                                 |                             |                          |
|---------------------------------|-----------------------------|--------------------------|
| Impedance                       | <b>50</b>                   | $\Omega$                 |
| Frequency                       | <b>0-65</b>                 | GHz                      |
| VSWR                            | <b>1.3*</b> + <b>0.0000</b> | x F(GHz) Maxi            |
| Insertion loss                  | <b>0.02+0.12*</b>           | $\sqrt{F}$ (GHz) dB Maxi |
| RF leakage                      | - ( <b>NA</b> )             | - F(GHz)) dB Maxi        |
| Voltage rating                  | <b>335</b>                  | Vrms Maxi                |
| Dielectric withstanding voltage | <b>500</b>                  | Vrms mini                |
| Insulation resistance           | <b>5000</b>                 | M $\Omega$ mini          |

### MECHANICAL CHARACTERISTICS

|                            |             |             |
|----------------------------|-------------|-------------|
| Center contact retention   |             |             |
| Axial force – Mating End   | <b>6.7</b>  | N mini      |
| Axial force – Opposite end | <b>6.7</b>  | N mini      |
| Torque                     | <b>NA</b>   | N.cm mini   |
| Recommended torque         |             |             |
| Mating                     | <b>NA</b>   | N.cm        |
| Panel nut                  | <b>NA</b>   | N.cm        |
| Mating life                | <b>50</b>   | Cycles Maxi |
| Weight                     | <b>0.41</b> | g Maxi      |

### ENVIRONMENTAL

|                       |                 |           |
|-----------------------|-----------------|-----------|
| Operating temperature | <b>-65/+165</b> | °C        |
| Hermetic seal         | <b>NA</b>       | Atm.cm3/s |
| Panel leakage         | <b>NA</b>       |           |

### SPECIFICATION

RAD-GEN-CONN-003  
RAD-DET-CONN-029

### OTHER CHARACTERISTICS

Assembly instruction:**NA**

Others:

**\*VSWR: 1.10(DC~26.5GHz);1.3(26.5~40GHz)**

**\*\*Coaxial transmission line only**

**Performance strongly depends on layout and PCB material**

### CUSTOMER APPROVAL

Company / department :

Name /date/signature:

Signed copy to be sent back to Radiall before any order.

Note : In case of compliant matrix, it must be signed and sent back too

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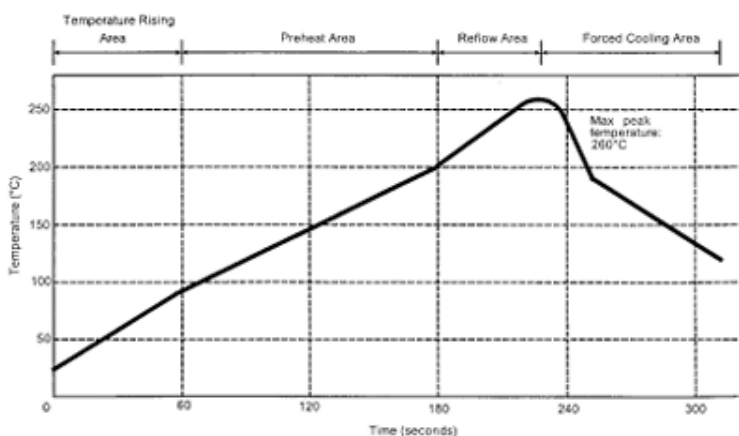
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### SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.  
We recommend a low residue flux.  
We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component .  
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

### TEMPERATURE PROFILE



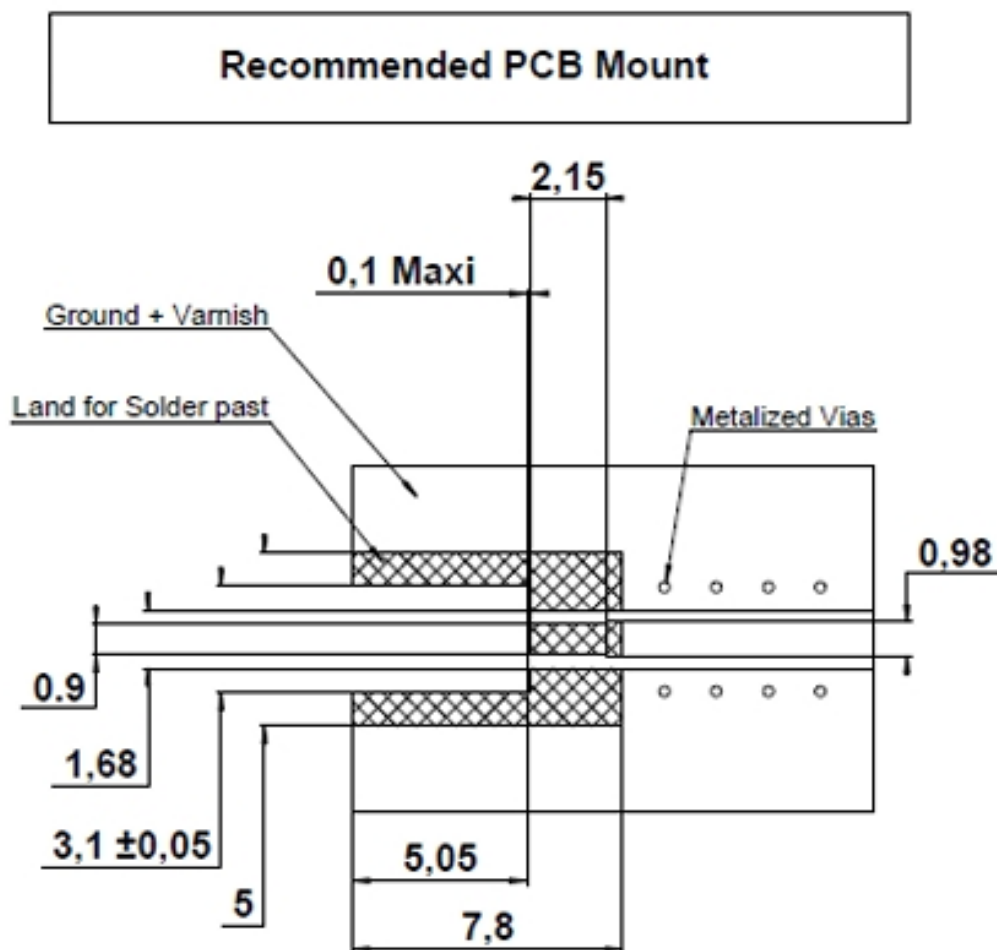
| Parameter                        | Value     | Unit   |
|----------------------------------|-----------|--------|
| Temperature rising Area          | 1 - 4     | °C/sec |
| Max Peak Temperature             | 260       | °C     |
| Max dwell time @260°C            | 10        | sec    |
| Min dwell time @235°C            | 20        | sec    |
| Max dwell time @235°C            | 60        | sec    |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C       | 420       | sec    |

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**Dimensions applicable for Roger RO4350 PCB material  
thickness 0.508 mm , with ground layer on bottom .  
Applicable Frequency - DC to 12Ghz**

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